

SN54ABT823, SN74ABT823 9-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCBS158E – JANUARY 1991 – REVISED MAY 1997

- State-of-the-Art **EPIC-IITM** BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Impedance State During Power Up and Power Down
- High-Drive Outputs (–32-mA I_{OH} , 64-mA I_{OL})
- Buffered Control Inputs to Reduce dc Loading Effects
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (NT) and Ceramic (JT) DIPs

description

These 9-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

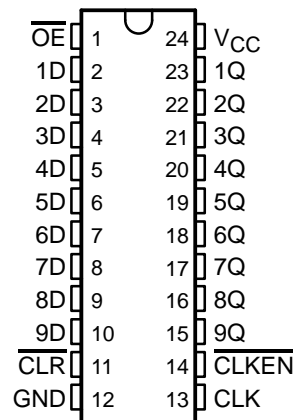
With the clock-enable ($\overline{\text{CLKEN}}$) input low, the nine D-type edge-triggered flip-flops enter data on the low-to-high transitions of the clock. Taking $\overline{\text{CLKEN}}$ high disables the clock buffer, thus latching the outputs. Taking the clear ($\overline{\text{CLR}}$) input low causes the nine Q outputs to go low, independently of the clock.

A buffered output-enable ($\overline{\text{OE}}$) input can be used to place the nine outputs in either a normal logic state (high or low logic level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

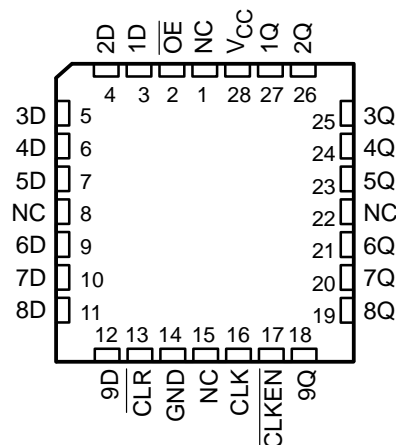
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT823 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT823 is characterized for operation from -40°C to 85°C .

SN54ABT823 . . . JT OR W PACKAGE
SN74ABT823 . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT823 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IITM is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1997, Texas Instruments Incorporated

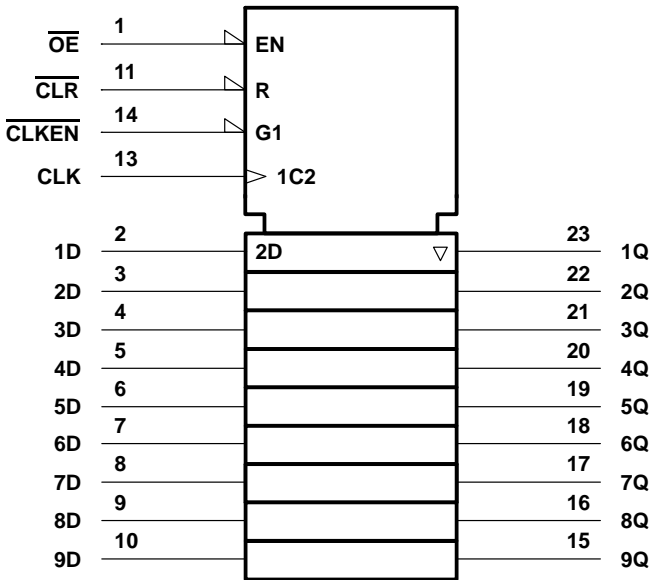
SN54ABT823, SN74ABT823
9-BIT BUS-INTERFACE FLIP-FLOPS
WITH 3-STATE OUTPUTS

SCBS158E – JANUARY 1991 – REVISED MAY 1997

FUNCTION TABLE
(each flip-flop)

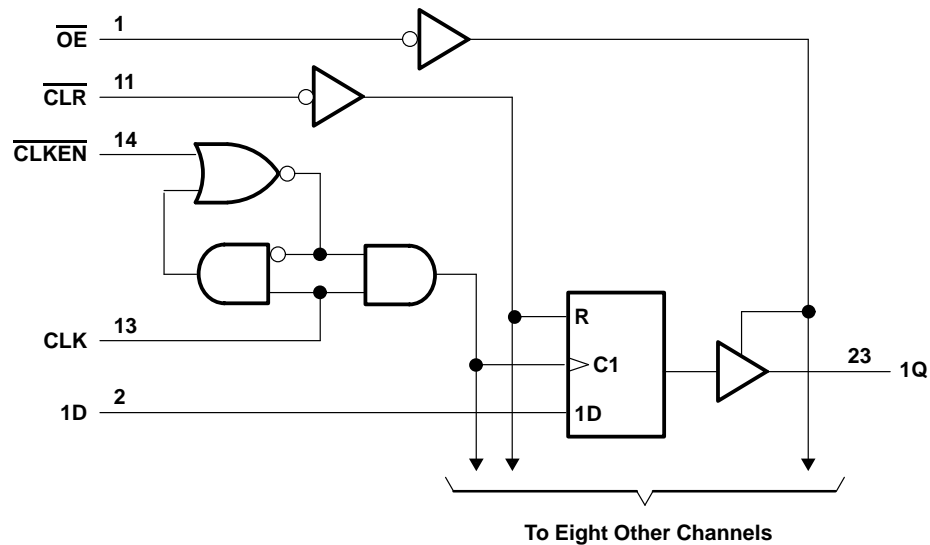
INPUTS					OUTPUT Q
OE	CLR	CLKEN	CLK	D	
L	L	X	X	X	L
L	H	L	↑	H	H
L	H	L	↑	L	L
L	H	H	X	X	Q ₀
H	X	X	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT823	96 mA
SN74ABT823	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
NT package	67°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the “recommended operating conditions” section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

SN54ABT823, SN74ABT823

9-BIT BUS-INTERFACE FLIP-FLOPS

WITH 3-STATE OUTPUTS

SCBS158E – JANUARY 1991 – REVISED MAY 1997

recommended operating conditions (see Note 3)

		SN54ABT823		SN74ABT823		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		–24		–32	mA
I _{OL}	Low-level output current		48		64	mA
Δt/Δv	Input transition rise or fall rate		5		5	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	200		200		μs/V
T _A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T _A = 25°C			SN54ABT823		SN74ABT823		UNIT
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA			–1.2		–1.2		–1.2	V
V _{OH}	V _{CC} = 4.5 V, I _{OH} = –3 mA	2.5			2.5		2.5		V
	V _{CC} = 5 V, I _{OH} = –3 mA	3			3		3		
	V _{CC} = 4.5 V	I _{OH} = –24 mA	2		2				
		I _{OH} = –32 mA	2*				2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA		0.55		0.55			V
		I _{OL} = 64 mA		0.55*				0.55	
V _{hys}			100						mV
I _I	V _{CC} = 5.5 V, V _I = V _{CC} or GND			±1		±1		±1	μA
I _{OZPU} ‡	V _{CC} = 0 to 2.1 V, V _O = 0.5 V to 2.7 V, $\overline{OE} = X$			±50		±50		±50	μA
I _{OZPD} ‡	V _{CC} = 2.1 V to 0, V _O = 0.5 V to 2.7 V, $\overline{OE} = X$			±50		±50		±50	μA
I _{OZH}	V _{CC} = 2.1 V to 5.5 V, V _O = 2.7 V, $\overline{OE} \geq 2$ V			10§		10§		10§	μA
I _{OZL}	V _{CC} = 2.1 V to 5.5 V, V _O = 0.5 V, $\overline{OE} \geq 2$ V			–10§		–10§		–10§	μA
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V			±100				±100	μA
I _{CEX}	V _{CC} = 5.5 V, V _O = 5.5 V			50		50		50	μA
I _O ¶	V _{CC} = 5.5 V, V _O = 2.5 V	–50	–140	–180	–50	–180	–50	–180	mA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		1	250	250		250	μA
		Outputs low		24	38	38		38	mA
		Outputs disabled		0.5	250	250		250	μA
ΔI _{CC} #	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			1.5		1.5		1.5	mA
C _i	V _I = 2.5 V or 0.5 V			4					pF
C _O	V _O = 2.5 V or 0.5 V			7					pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ This parameter is characterized, but not production tested.

§ This data sheet limit may vary among suppliers.

¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54ABT823, SN74ABT823 9-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCBS158E – JANUARY 1991 – REVISED MAY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$		SN54ABT823		SN74ABT823		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	125	0	125	0	125	MHz
t_w	Pulse duration	CLR low	5.5	5.5	5.5			ns
		CLK high	2.9	2.9	2.9			
		CLK low	3.8	3.8	3.8			
t_{su}	Setup time before CLK \uparrow	CLR inactive	2.5	2.5	2.5			ns
		Data	2.1	2.1	2.1			
		CLKEN high	2	2	2			
		CLKEN low	3.3	3.3	3.3			
t_h	Hold time after CLK \uparrow	Data	1.3	1.3	1.3			ns
		CLKEN high	1	1	1			
		CLKEN low	2	2	2			

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$			SN54ABT823		SN74ABT823		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			125	200		125		125		MHz
t_{PLH}	CLK	Q	2.1	4.3	5.9	2.1	8.1	2.1	6.8	ns
t_{PHL}			2.2	4.4	6.1	2.2	7	2.2	6.7	
t_{PHL}	$\overline{\text{CLR}}$	Q	2	4.1	6.3	2	7.3	2	7.1	ns
t_{PZH}	$\overline{\text{OE}}$	Q	1	3	4.7 \dagger	1	6.3	1	6 \dagger	ns
t_{PZL}			2.2	4.1	5.6	2.2	6.6	2.2	6.5 \dagger	
t_{PHZ}	$\overline{\text{OE}}$	Q	2.7	4.8	6.5 \dagger	2.7	7.7	2.7	7.5 \dagger	ns
t_{PLZ}			1.9	5	6.4	1.9	7.4	1.9	6.9	

\dagger This data sheet limit may vary among suppliers.

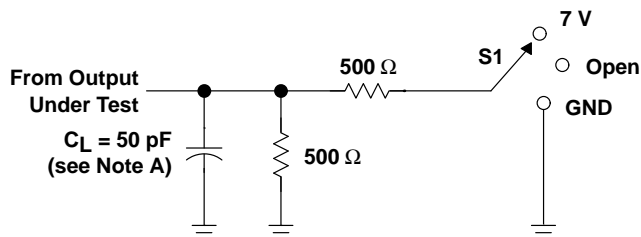
SN54ABT823, SN74ABT823

9-BIT BUS-INTERFACE FLIP-FLOPS

WITH 3-STATE OUTPUTS

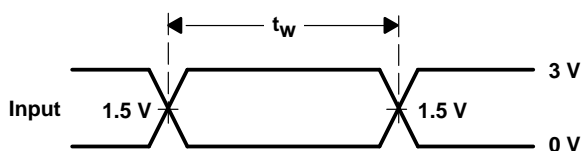
SCBS158E – JANUARY 1991 – REVISED MAY 1997

PARAMETER MEASUREMENT INFORMATION

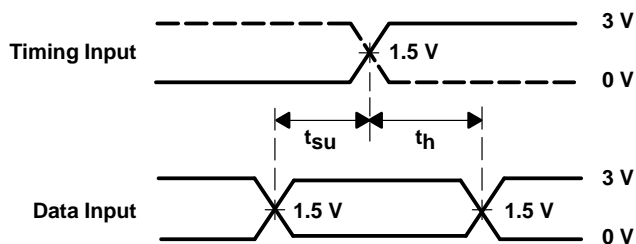


LOAD CIRCUIT

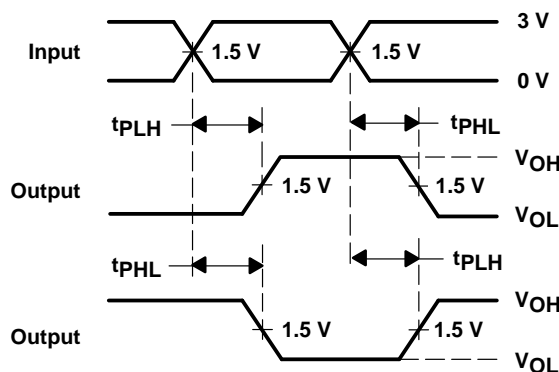
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



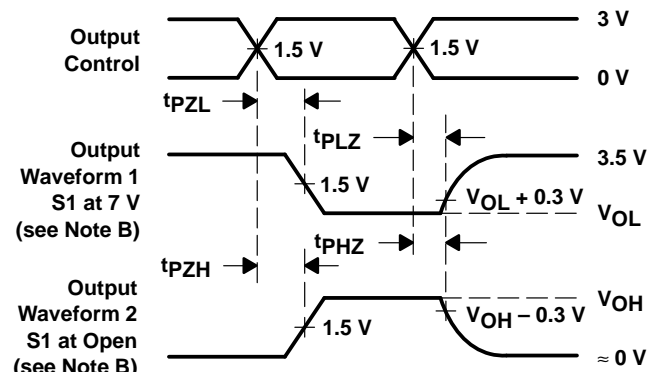
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.